

U.S. Department of Commerce, Patent and Trademark Office					Atty Docket No.		Serial No.	
					M-12589 US		10/080,468	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT					Applicant(s)			
(Use several sheets if necessary)					Hua Ji			
					Filing Date		Group	
					February 22, 2002		Unknown	
U.S. Patent Documents								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
A.M	AA	5,872,058	02/16/99	Van Cleemput et al.	438	692		
	AB	6,030,881	02/29/00	Papasouliotis et al.	438	424		
	AC	6,136,685	10/24/00	Narwankar et al.	438	624		
	AD	6,211,040 B1	04/03/01	Liu et al.	438	424		
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
A.M	AQ	Schravendijk, et al., "Dielectric Gap Fill Technology for STI for the 0.10 $\mu$ m Era", Novellus Systems, Inc., 6 pages						
A.M	AR	Conti, et al., "Processing Methods to Fill High Aspect Ratio Gaps Without Premature Constriction," DUMIC Conference 1999, pages 201-209						
	AS							
Examiner		ANH D. MAJ		Date Considered 11/14/02				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.								